WORKSHOP

Sunday, May 14, 1995

ICs For Wireless Communications: Design, Packaging & Test Issues

Location: CC-A1
Time: 8:30 am–5:00 pm
Sponsors: MTT-6 Microwave and Millimeter-Wave ICs
TPC-1995 MMWMC Symposium
MTT-16 Microwave Systems
Organizers & Moderators: Fazai Ali, Westinghouse—ATD
Burnie Geller, David Sarnoff Research Center
Mike Golio, Motorola
Speakers: Peter Bachert, RF Micro Devices
Richard Koyama, Triquint Semiconductor
Kevin Negus, Hewlett Packard
Phil Wallace, Anadigics
Dave Halcin, Motorola
Peter Bacon, Raytheon
Finbarr McGrath, M/A COM
Sarjit Bharj, David Sarnoff Research Center
Christian Kermarrec, Analog Devices
Mark McDonald, National Semiconductor
David Smith, GEC-Marconi
Shinji Hara, Sharp Corp.
M. Muraguchi, NTT
John Barr, Hewlett Packard

Abstract:

This one day workshop will acquaint participants with the specific IC design, packaging and test requirements for the emerging wireless communication applications. Application areas to be covered include: cellular/personal communication systems (PCS), wireless local network area networks (WLANs), satellite communications and navigation. IC designs based on Silicon Bipolar, BiCMOS, CMOS, SiGe and GaAs technologies will be covered. Invited speakers will also discuss modeling, simulation and manufacturing issues related to low cost, high volume commercial markets.